



Product Description

The SGA0363Z is a high performance SiGe HBT MMIC Amplifier. A Darlington configuration featuring one-micron emitters provides high F_T and excellent thermal performance. The heterojunction increases breakdown voltage and minimizes leakage current between junctions. Cancellation of emitter junction non-linearities results in higher suppression of intermodulation products. Only two DC-blocking capacitors, a bias resistor and an optional RF choke are required for operation.

Features

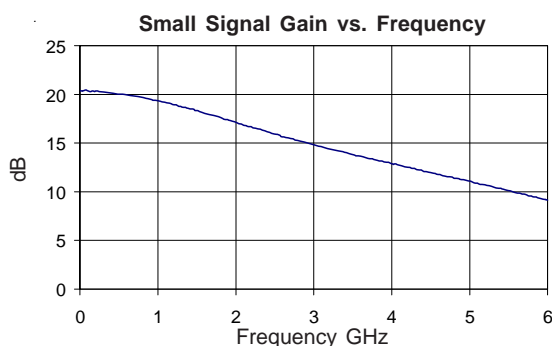
- DC to 5000MHz Operation
- Single Voltage Supply
- Low Current Draw: 11mA at 2.5V Typ.
- High Output Intercept: 14dBm Typ. at 1950MHz

Applications

- PA Driver Amplifier
- Cellular, PCS, GSM, UMTS
- IF Amplifier
- Wireless Data, Satellite

Optimum Technology Matching® Applied

- ☐ GaAs HBT
- ☐ GaAs MESFET
- ☐ InGaP HBT
- ☐ SiGe BiCMOS
- ☐ Si BiCMOS
- ☒ SiGe HBT
- ☐ GaAs pHEMT
- ☐ Si CMOS
- ☐ Si BJT
- ☐ GaN HEMT
- ☐ RF MEMS



Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Output Power at 1dB Compression		2.3		dBm	850MHz
		2.3		dBm	1950MHz
		1.6		dBm	2400MHz
Third Order Intercept Point		14.2		dBm	850MHz
		14.0		dBm	1950MHz
		13.1		dBm	2400MHz
Small Signal Gain		19.6		dB	850MHz
		17.2		dB	1950MHz
		16.2		dB	2400MHz
3dB Bandwidth		5000		MHz	
Input VSWR		1.8:1			DC to 4500MHz
Output VSWR		1.7:1			DC to 4500MHz
Reverse Isolation		24.0		dB	850MHz
		22.8		dB	1950MHz
		22.1		dB	2400MHz
Noise Figure ^[1]		3.0		dB	1950MHz
Device Operating Voltage		2.5		V	
Device Operating Current	9	11	13	mA	
Thermal Resistance		255		°C/W	junction - lead

Test Conditions: $V_S=5V$, $I_D=11mA$ Typ., $T_L=25^\circ C$. OIP3 Tone Spacing=1MHz, P_{OUT} per tone=-12dBm, $R_{BIAS}=220\Omega$, $Z_S=Z_L=50\Omega$

Absolute Maximum Ratings

Parameter	Rating	Unit
Device Current (I_D)	22	mA
Device Voltage (V_D)	6	V
RF Input Power	-5	dBm
Junction Temp (T_J)	+150	°C
Operating Temp Range (T_L)	-40 to +85	°C
Storage Temp	+150	°C

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation, the device voltage and current must not exceed the maximum operating values specified in the table on page one.

Bias Conditions should also satisfy the following expression:

$$I_D V_D < (T_J - T_L) / R_{TH, J-I}$$



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

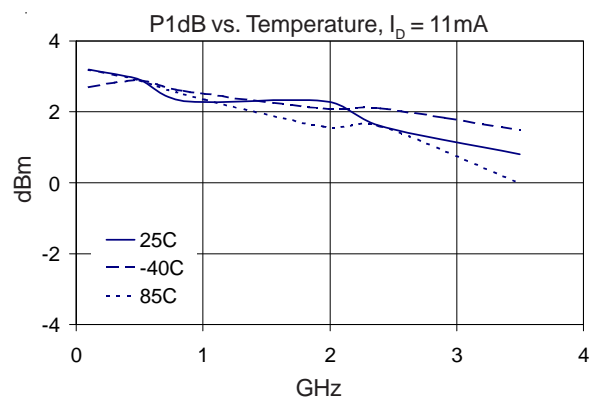
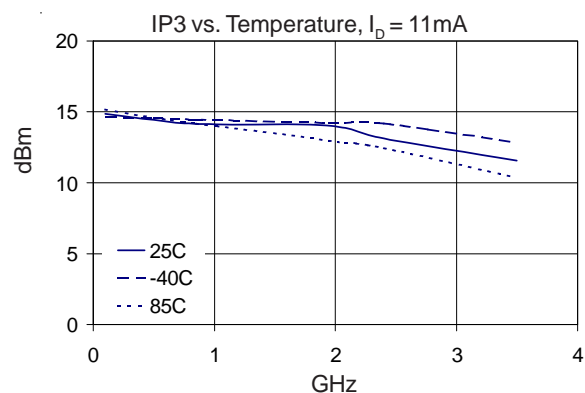
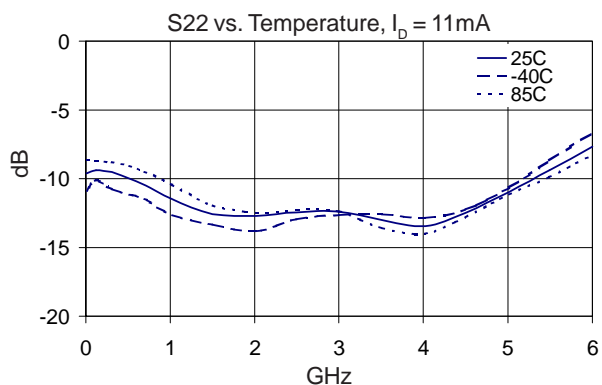
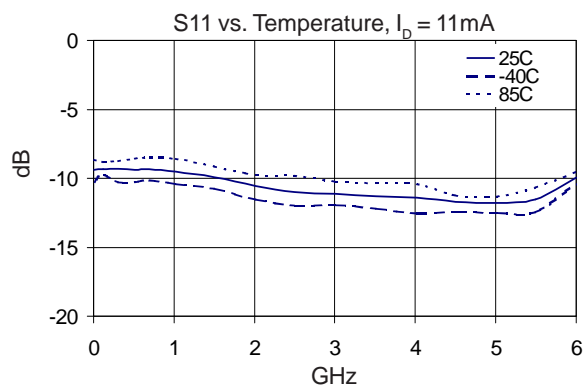
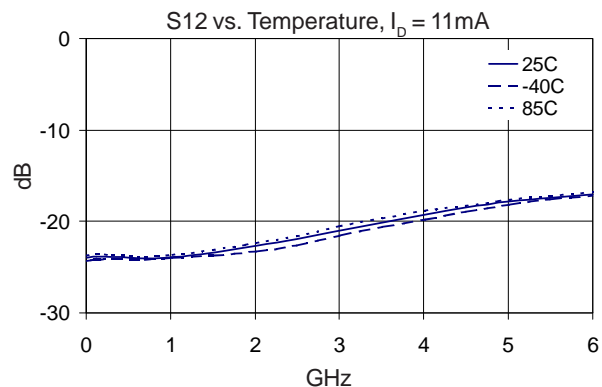
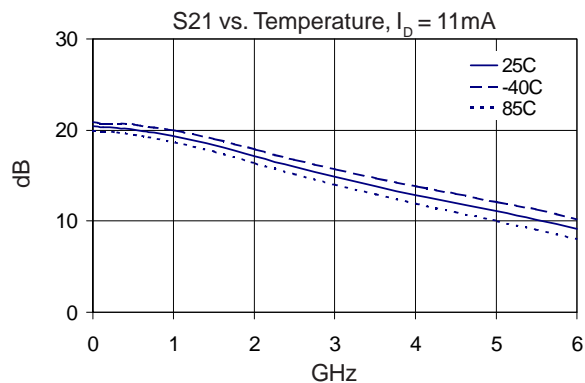
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RFMD Green: RoHS compliant per EU Directive 2002/95/EC, halogen free per IEC 61249-2-21, < 1000ppm each of antimony trioxide in polymeric materials and red phosphorus as a flame retardant, and <2% antimony in solder.

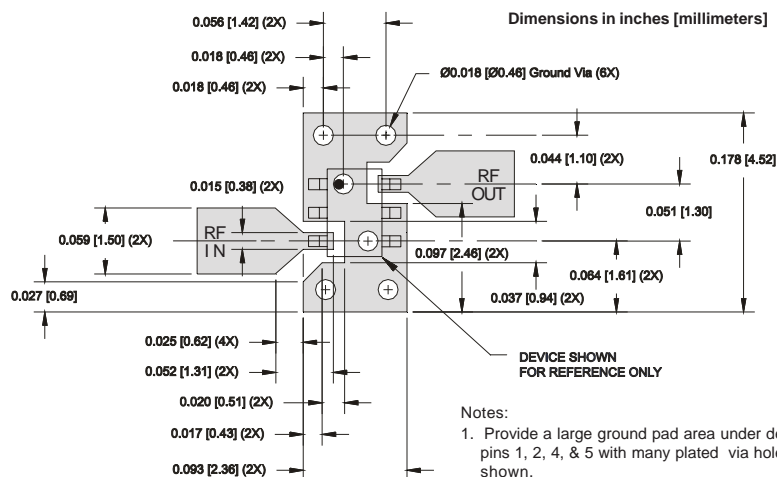
Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
Gain		20.4		dB	100MHz
		20.0		dB	500MHz
		19.6		dB	850MHz
		17.2		dB	1950MHz
		16.2		dB	2400MHz
Output IP_3		13.8		dB	3500MHz
		14.8		dBm	100MHz, Tone spacing=1MHz, P_{OUT} per tone=-12dBm
		14.5		dBm	500MHz, Tone spacing=1MHz, P_{OUT} per tone=-12dBm
		14.2		dBm	850MHz, Tone spacing=1MHz, P_{OUT} per tone=-12dBm
		14.0		dBm	1950MHz, Tone spacing=1MHz, P_{OUT} per tone=-12dBm
		13.1		dBm	2400MHz, Tone spacing=1MHz, P_{OUT} per tone=-12dBm
Output P1dB		11.5		dBm	3500MHz, Tone spacing=1MHz, P_{OUT} per tone=-12dBm
		3.2		dBm	100MHz
		2.9		dBm	500MHz
		2.3		dBm	850MHz
		2.3		dBm	1950MHz
		1.6		dBm	2400MHz
Input Return Loss		0.8		dBm	3500MHz
		9.3		dB	100MHz
		9.4		dB	500MHz
		9.4		dB	850MHz
		10.4		dB	1950MHz
		10.8		dB	2400MHz
Reverse Isolation		11.3		dB	3500MHz
		23.9		dB	100MHz
		23.9		dB	500MHz
		24.0		dB	850MHz
		22.8		dB	1950MHz
		22.1		dB	2400MHz
Noise Figure		20.1		dB	3500MHz
		2.9		dB	100MHz, $Z_S=50\Omega$
		2.8		dB	500MHz, $Z_S=50\Omega$
		3.0		dB	850MHz, $Z_S=50\Omega$
		3.0		dB	1950MHz, $Z_S=50\Omega$

Test Conditions: $I_D=8mA$, unless otherwise noted



Pin	Function	Description
3	RF IN	RF input pin. This pin requires the use of an external DC blocking capacitor chosen for the frequency of operation.
1, 2, 4, 5	GND	Connection to ground. Use via holes for best performance to reduce lead inductance as close to ground leads as possible.
6	RF OUT/BIAS	RF output and bias pin. DC voltage is present on this pin, therefore a DC blocking capacitor is necessary for proper operation.

Suggested Pad Layout



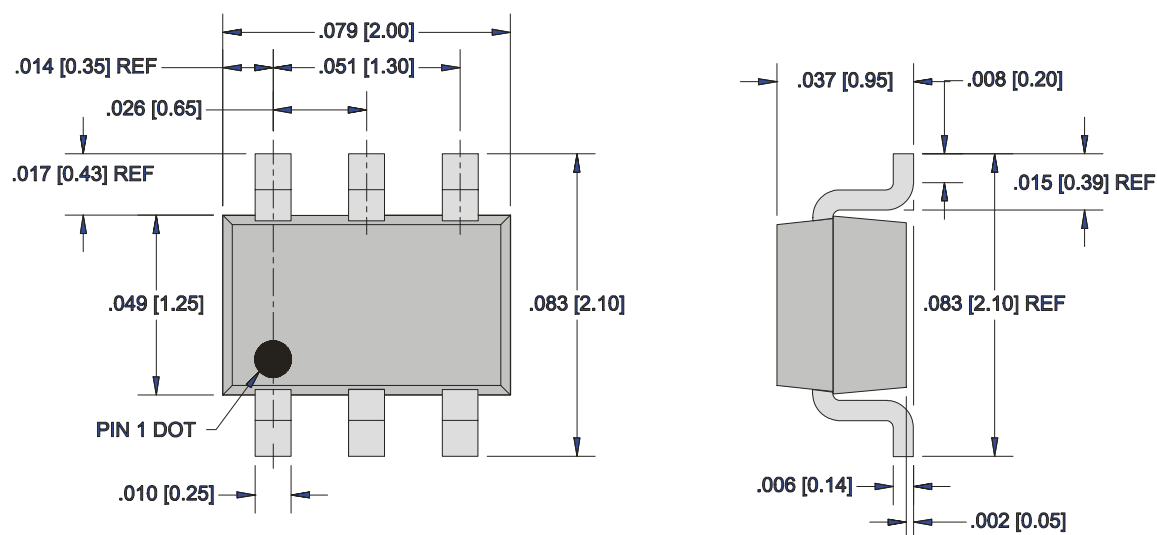
Notes:

1. Provide a large ground pad area under device pins 1, 2, 4, & 5 with many plated via holes as shown.
2. Dimensions given for 50 Ohm RF I/O lines are for 31 mil thick Getek. Scale accordingly for different board thicknesses and dielectric constants.
3. We recommend 1 or 2 ounce copper. Measurements for this data sheet were made on a 31 mil thick Getek with 1 ounce copper on both sides.

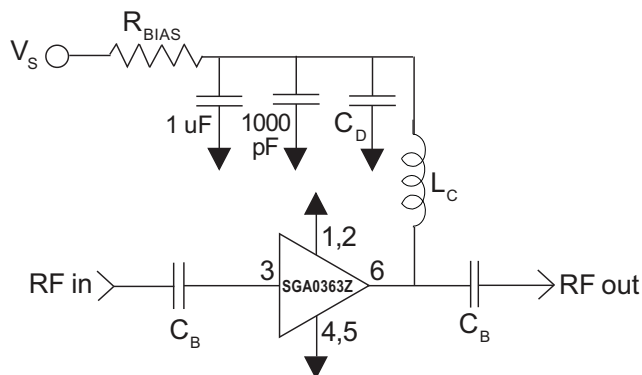
Package Drawing

Dimensions in inches (millimeters)

Refer to drawing posted at www.rfmd.com for tolerances.



Application Schematic



Reference Designator	Frequency (Mhz)				
	500	850	1950	2400	3500
C _B	220 pF	100 pF	68 pF	56 pF	39 pF
C _D	100 pF	68 pF	22 pF	22 pF	15 pF
L _C	68 nH	33 nH	22 nH	18 nH	15 nH

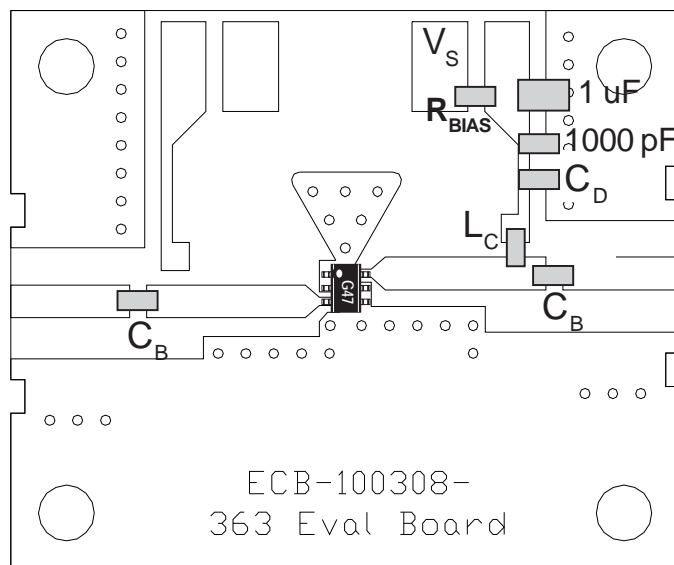
Recommended Bias Resistor Values for I_D=11mA

$$R_{BIAS} = (V_S - V_D) / I_D$$

Supply Voltage(V _S)	5 V	7.5 V	9 V	12 V
R _{BIAS}	220 Ω	470 Ω	620 Ω	910 Ω

Note: R_{BIAS} provides DC bias stability over temperature.

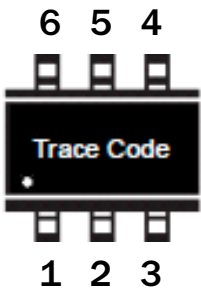
Evaluation Board Layout



Mounting Instructions

1. Use a large ground pad area near device pins 1, 2, 4, and 5 with many plated through-holes as shown.
2. We recommend 1 or 2 ounce copper. Measurements for this data sheet were made on a 31 mil thick FR-4 board with 1 ounce copper on both sides.

Part Identification Marking



Ordering Information

Ordering Code	Description
SGA0363Z	7" Reel with 3000 pieces
SGA0363ZSQ	Sample bag with 25 pieces
SGA0363ZSR	7" Reel with 100 pieces
SGA0363Z-EVB1	850MHz, 5V Operation PCBA